

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

1. (original) A semiconductor device comprising:

a semiconductor chip;

a plurality of leads arranged around the semiconductor chip;

terminals connected to the plural leads respectively;

a plurality of wires for connecting the semiconductor chip and the plural leads electrically with each other; and

a resin sealing member for sealing the semiconductor chip, the plural leads and the plural wires;

the terminals connected respectively to the plural leads being exposed to the exterior from a back surface of the sealing member,

wherein one ends of the plural leads are exposed to the exterior from side faces of the resin sealing member and are covered throughout the whole peripheries thereof with resin which constitutes the resin sealing member.

2. (original) A semiconductor device according to claim 1, wherein the semiconductor chip is mounted over a

die pad portion supported by a plurality of suspension leads, one end of each of the plural suspension leads is branched in the vicinity of a corner of the resin sealing member, the branched lead portions are exposed to side faces of the resin sealing member, and the whole peripheries of the exposed, branched lead portions are covered with the resin which constitutes the resin sealing member.

3. (original) A semiconductor device according to claim 1, wherein the semiconductor chip is mounted over a die pad portion supported by a plurality of suspension leads, one end of each of the plural suspension leads is exposed to the exterior from side faces of the resin sealing member at a corner of the resin sealing member, and the whole periphery thereof is covered with the resin which constitutes the resin sealing member.

4. (original) A semiconductor device according to claim 2, wherein the plural suspension leads are each partially exposed to the exterior from a back surface of the resin sealing member.

5. (original) A semiconductor device according to claim 1, wherein the terminals are respectively constituted such that portions of the leads are projected to the exterior from a back surface of the resin sealing member.

6. (original) A semiconductor device according to claim 1, wherein the terminals are formed of an electrically conductive material different from the material of the leads.

7. (original) A semiconductor device according to claim 2, wherein a back surface of the die pad portion is partially exposed to the exterior from a back surface of the resin sealing member.

8. (original) A semiconductor device according to claim 1, wherein, in each of the plural leads, the thickness of its portion positioned outside its terminal-connected portion is larger than its portion positioned inside its terminal-connected portion.

9. (original) A semiconductor device according to claim 1, wherein the semiconductor chip is mounted over a

sheet-like chip support, and the chip support is supported by a plurality of leads.

10. (original) A semiconductor device according to claim 1, wherein the terminals are arranged zigzag in two rows along the sides of the resin sealing member.

11. (original) A semiconductor device according to claim 3, wherein the area of the die pad portion is smaller than the area of the semiconductor chip.

Claims 12-15 (canceled)